BS IEC 62047-47:2024

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Semiconductor devices — Micro-electromechanical devices

Part 47: Silicon based MEMS fabrication technology — Measurement method of bending strength of microstructures

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The UK participation in its preparation was entrusted to Technical Committee EPL/47, Semiconductors.

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Published by BSI Standards Limited 2024

ISBN 978 0 539 21851 0

ICS 31.080.99

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This British Standard was published under the authority of the Standards Policy and Strategy Committee on 31 August 2024.

Amendments/corrigenda issued since publication

Date	Text affected

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Full document details: BS IEC 62047-47:2024

IEC 62047-47

Edition 1.0 2024-08

INTERNATIONAL STANDARD

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Semiconductor devices – Micro-electromechanical devices – Part 47: Silicon based MEMS fabrication technology – Measurement method of bending strength of microstructures

INTERNATIONAL
ELECTROTECHNICAL
COMMISSION

ICS 31.080.99

ISBN 978-2-8322-9556-4

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CONTENTS

FOREWORD 3
1 Scope 5
2 Normative references 5
3 Terms and definitions 5
4 Requirements 6
4.1 In-situ on-chip tester design requirements 6
4.2 In-situ on-chip tester fabrication requirements 8
4.3 Testing environment requirements 8
5 Testing method 8
5.1 General 8
5.2 Microstructure bending strength testing method operation process 8
5.3 Microstructure bending strength testing method result process 9
6 Test report 10
Annex A (informative) Examples of bending strength testing for microstructures 11
A.1 General 11
A.2 Design dimensions of the testing device 11
A.3 Microstructures bending strength test 14
Bibliography 16

Figure 1 – The in-situ on-chip bending strength tester 6
Figure 2 – Three-view drawing of the testing structure 7
Figure 3 – Microstructure bending strength testing method operation process 8
Figure 4 – Scheme of the beam of constant strength 9
Figure 5 – Scheme of the magnifying lever 9
Figure 6 – Scheme of the elastic beam 10
Figure A.1 – Overall dimension labelling of the testing device 11
Figure A.2 – Local dimension labelling of the testing device 12
Figure A.3 – Design of the deflection ruler and the displacement ruler 13
Figure A.4 – Test area 15

Table 1 – Dimensions for testing structure 9
Table A.1 – Design dimensions of the testing device 14
Table A.2 – Microstructure bending strength test results 15

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SEMICONDUCTOR DEVICES – MICRO-ELECTROMECHANICAL DEVICES –

Part 47: Silicon based MEMS fabrication technology – Measurement method of bending strength of microstructures

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The text of this International Standard is based on the following documents:

Draft	Report on voting
47F/474/FDIS	47F/481/RVD

Full information on the voting for its approval can be found in the report on voting indicated in the above table.

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The language used for the development of this International Standard is English.

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